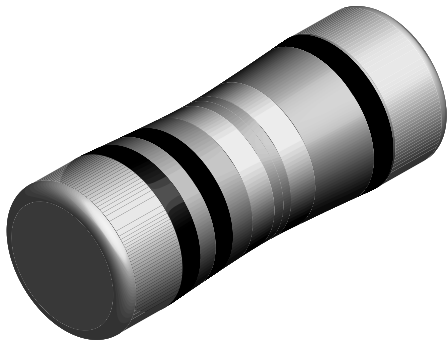


Metal Film, Cylindrical, Fusible Resistors



FEATURES

- Fusible resistor for constant current designed for overload protection
- High positive temperature coefficient
- Flame retardant coating
- Defined switch-off behaviour

STANDARD ELECTRICAL SPECIFICATIONS					
MODEL	POWER RATING $P_{70^{\circ}\text{C}}^{1)}$ W	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES
NMM0207SI	0.35	+ 4500/± 500	5, 10, 20	1R0 – 47R	12 – 24
NMM0207SI	0.35	+ 4500/± 500	10, 20	R10 – R91	12

¹⁾ Power rating depends on the maximum temperature at the solder point, the component placement density and the substrate material.

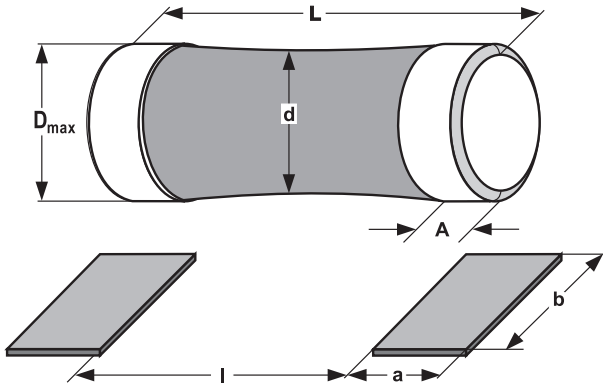
- Coating: beige
- Marking: additional 5th band black; for further information see appropriate catalog or web page

TECHNICAL SPECIFICATIONS		
PARAMETER	UNIT	NMM0207SI
Rated Dissipation at 70°C	W	0.35
Minimum Overload to Fuse	W	1.5
Time to Fuse (max)	s	30
Max. applicable Voltage after Fusing	V	85
Thermal Resistance	K/W	≤ 220
Category Temperature Range	°C	- 55 / + 125
Failure Rate	10^{-9} /h	< 30
Weight / 1000pcs	g	71

PACKAGING: See SMM0207

ORDERING INFORMATION				
NMM0207SI	+ 4500 / ± 500	36R	5%	BP
MODEL	TC ppm / K	RESISTANCE VALUE Ω	TOLERANCE ± %	PACKAGING BP-Blistertape 1500 pcs

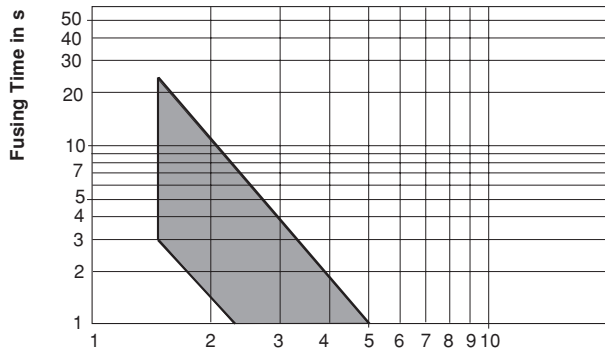
DIMENSIONS



MODEL	DIMENSIONS [in millimeters]				
	D _{max}	d *	L	A _{max}	A _{min}
NMM0207SI	2.2	D -0.4	5.8 - 0.3	1.2	0.6

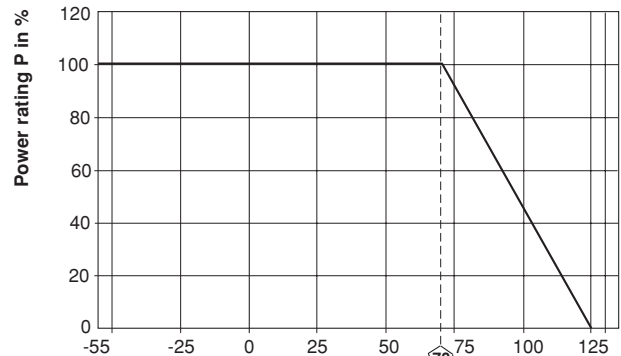
* d measured in the middle of the resistor

MODEL	SOLDER PAD DIMENSIONS [in millimeters]					
	REFLOW SOLDERING			WAVE SOLDERING		
	a	b	l	a	b	l
NMM0207SI	1.8	2.5	2.9	2.4	2.5	2.8



Fusing Performance

Power in W



Derating

Ambient Temp. in °C

PERFORMANCE		
TEST	CONDITIONS OF TEST	REQUIREMENTS
Endurance Test at 70°C IEC 60115-1 4.25.1	1000 hours at 70°C, 1.5 hours "ON", 0.5 hours "OFF"	≤ ± 2 %
Endurance at UCT IEC 60115-1 4.25.3	1000 hours at 125°C without load	≤ ± 2 %
Overload Test IEC 60115-1 4.13	Short time overload for 2 seconds	≤ ± 2 %
Thermal Shock IEC 60115-1 4.19 IEC 60068-2-14	Rapid change between upper and lower category temperature	≤ ± 2 %
Damp Heat Steady State IEC 60115-1 4.24 IEC 60068-2-3	56 days at 40°C and 93% relative humidity	≤ ± 2 %
Resistance to Soldering Heat IEC 60115-1 4.18 IEC 60068-2-20	10 seconds at 260°C solder bath temperature	≤ ± 1 %

SOLDERING INFORMATION
<ul style="list-style-type: none"> • For reflow soldering only • Board has to be thoroughly cleaned after soldering. All flux materials must be completely removed.

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.